



FORM PTO-1595
(Rev. 6-93)

103418683

RECORDATION FORM COVER SHEET
PATENTS ONLY

Attorney Docket No.: 065542-5050

To the Commissioner for Patents
Please record the attached original documents or copy thereof.

ATTN: MAIL STOP ASSIGNMENT RECORDATION SERVICES

06/13/07

1. Name of conveying party(ies):
Sung-Gyu PYO
Dong-Joon KIM

Additional names of conveying party(ies) attached?
 Yes No

2. Name and address of receiving party(ies):
Name: MagnaChip Semiconductor Ltd.

Internal Address:

Street Address: 1, Hyangjeong-dong, Heungduk-gu
Cheongju-si, Chungcheongbuk-do
361-725, Republic of Korea

City:
State: Zip:

Additional name(s) & address(es) attached?
 Yes No

3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other _____
Execution Date: May 30, 2007

4. New Application number(s) or patent number(s): **NEW APPLICATION**

If this document is being filed together with a new application the execution date of the application is:

May 30, 2007
A. Patent Application No.(s) B. Patent No.(s)

Additional numbers attached: Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Collin W. Park

Internal Address: Morgan, Lewis & Bockius LLP
Customer No. 09629

Street Address: 1111 Pennsylvania Ave., N.W.
City: Washington State: D.C. Zip: 20004

6. Total number of applications and patents involved: 1

7. Total fee (37 C.F.R. §3.41): \$40.00
 Enclosed
 Authorized to be charged to Deposit Account 50-0310

8. Deposit Account No. 50-0310
(Attach duplicate page if paying by deposit account)

9. Statement and Signature
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Collin W. Park, Reg. No. 43,378
Name of Person Signing

Collin W. Park
Signature

June 13, 2007
Date

Total number of pages including cover sheet, attachments and documents: 2

06/25/2007 DBYRNE 00000011 500310 11808877
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ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:
 PACKAGE OF MEMS DEVICE AND METHOD FOR FABRICATING THE SAME

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on _____, (Serial No. _____); and

WHEREAS, MagnaChip Semiconductor Ltd., a corporation of Republic of Korea, whose post office address is 1 Hyangjeong-dong, Heungbuk-gu, Cheongju-si, Chungcheongbuk-do, 361-725, Republic of Korea, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. _____, filed 13JUN2007) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Full Name of Sole or First Assignor PYO, Sung-Gyu	Assignor's Signature <i>[Signature]</i>	Date 30/05/2007
Address: 1 Hyangjeong-dong, Heungbuk-gu, Cheongju-si, Chungcheongbuk-do, 361-725, Republic of Korea		Citizenship Republic of Korea
Full Name of Second Assignor KIM, Dong-Joon	Assignor's Signature <i>[Signature]</i>	Date 20/05/2007
Address: 1 Hyangjeong-dong, Heungbuk-gu, Cheongju-si, Chungcheongbuk-do, 361-725, Republic of Korea		Citizenship Republic of Korea
Full Name of Third Assignor	Assignor's Signature	Date
Address:		Citizenship
Full Name of Fourth Assignor	Assignor's Signature	Date
Address:		Citizenship
Names of additional inventors attached <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		

Morgan, Lewis & Bockius LLP

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